

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.0239	100.0	0.48
			Subtotal	0.0239	100	0.48
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03741	100.0	0.75148
			Subtotal	0.03741	100	0.75148
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00054	2.0	0.0108
	Lead alloy	Silver (Ag)	7440-22-4	0.00067	2.5	0.0135
	Lead alloy	Lead (Pb)	7439-92-1	0.02567	95.5	0.5157
			Subtotal	0.02688	100	0.54
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.74673	100.0	15
			Subtotal	0.74673	100	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02116	0.03	0.4251
	Copper alloy	Iron (Fe)	7439-89-6	0.07054	0.1	1.417
	Copper alloy	Copper (Cu)	7440-50-8	70.30784	99.67	1,412.3239
	Copper alloy	Silver (Ag)	7440-22-4	0.14108	0.2	2.834
			Subtotal	70.54062	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.86059	6.5	37.375
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.57991	16.0	92
	Filler	Silica fused	60676-86-0	20.32337	71.0	408.25
	Flame retardant	Metal hydroxide		1.86059	6.5	37.375
			Subtotal	28.62446	100	575
			Total	100	100	NaN

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